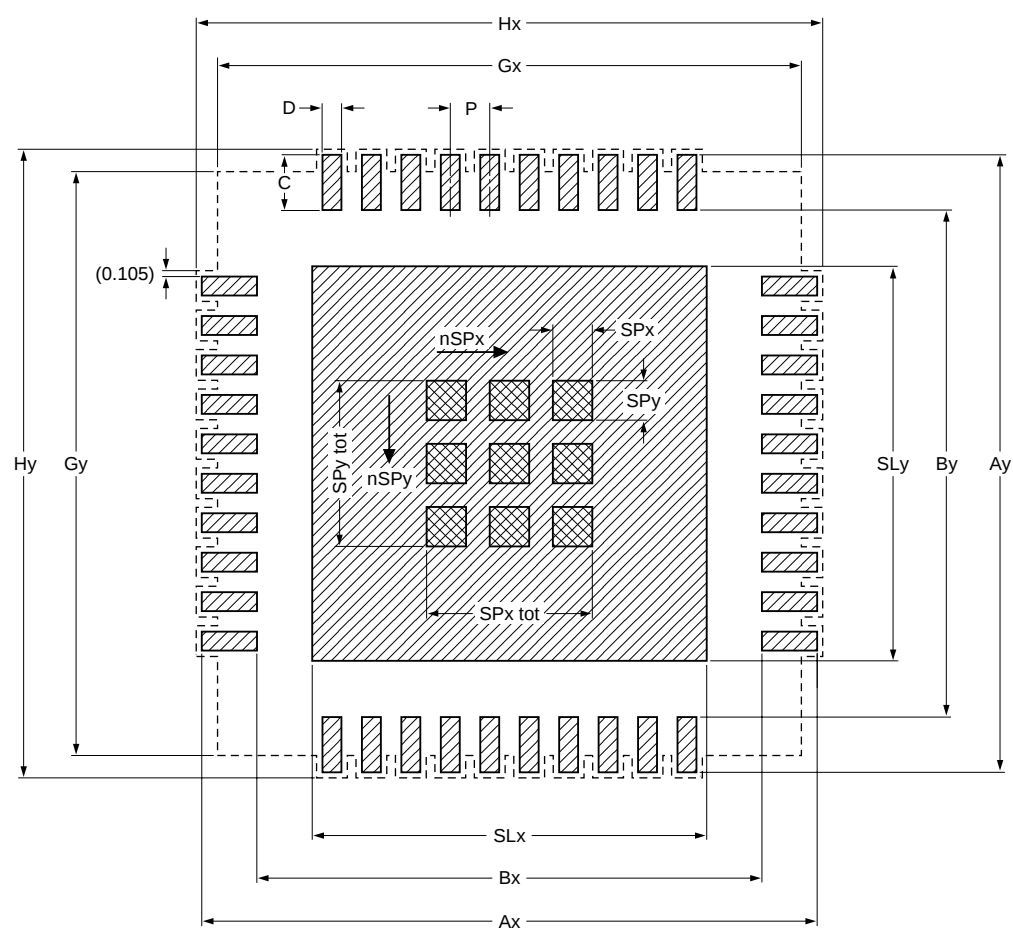


Footprint information for reflow soldering of HVQFN56 package

SOT684-1



- Generic footprint pattern
Refer to the package outline drawing for actual layout
-  solder land
 -  solder paste deposit
 -  solder land plus solder paste
 - occupied area

nSPx	nSPy
3	3

DIMENSIONS in mm

P	Ax	Ay	Bx	By	C	D	SLx	SLy	SPx tot	SPy tot	SPx	SPy	Gx	Gy	Hx	Hy
0.500	9.000	9.000	7.200	7.200	0.900	0.290	4.300	4.300	2.500	2.500	0.650	0.650	8.300	8.300	9.250	9.250